

# IP4285CZ6-TD

## ESD protection for high-speed interfaces

Rev. 4 — 21 March 2014

Product data sheet

## 1. Product profile

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### 1.1 General description

The device is designed to protect high-speed interfaces such as USB 2.0 ports against ElectroStatic Discharge (ESD).

The device includes four high-level ESD protection diode structures for high-speed signal lines. It is encapsulated in a small SOT457 (SC-74) Surface-Mounted Device (SMD) plastic package.

All signal lines are protected by a special diode configuration offering ultra low line capacitance of 0.85 pF maximum. This configuration provides protection to downstream components from ESD voltages up to  $\pm 12$  kV contact according to IEC 61000-4-2, level 4.

### 1.2 Features and benefits

- System ESD protection for USB 2.0
- All signal lines with integrated rail-to-rail clamping diodes for downstream ESD protection of  $\pm 12$  kV according to IEC 61000-4-2, level 4
- Line capacitance of 0.85 pF maximum for each channel

### 1.3 Applications

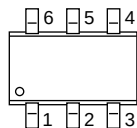
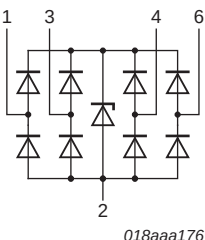
The device is designed for receiver and transmitter port protection in:

- Portable devices
- TVs, monitors
- DVD recorders and players
- Notebooks, mother boards, graphic cards and ports
- Set-top boxes and game consoles



## 2. Pinning information

Table 1. Pinning

| Pin | Description                    | Simplified outline                                                                 | Graphic symbol                                                                      |
|-----|--------------------------------|------------------------------------------------------------------------------------|-------------------------------------------------------------------------------------|
| 1   | ESD protection for I/O signals |  |  |
| 2   | ground                         |                                                                                    |                                                                                     |
| 3   | ESD protection for I/O signals |                                                                                    |                                                                                     |
| 4   | ESD protection for I/O signals |                                                                                    |                                                                                     |
| 5   | n.c.                           |                                                                                    |                                                                                     |
| 6   | ESD protection for I/O signals |                                                                                    |                                                                                     |

## 3. Ordering information

Table 2. Ordering information

| Type number  | Package |                                          |         |
|--------------|---------|------------------------------------------|---------|
|              | Name    | Description                              | Version |
| IP4285CZ6-TD | SC-74   | plastic surface-mounted package; 6 leads | SOT457  |

## 4. Marking

Table 3. Marking codes

| Type number  | Marking code |
|--------------|--------------|
| IP4285CZ6-TD | 85           |

## 5. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol    | Parameter                       | Conditions                                              | Min  | Max  | Unit |
|-----------|---------------------------------|---------------------------------------------------------|------|------|------|
| $V_I$     | input voltage                   |                                                         | -0.5 | +5.5 | V    |
| $V_{ESD}$ | electrostatic discharge voltage | pins 1, 3, 4 and 6 to ground;<br>IEC 61000-4-2, level 4 |      |      |      |
|           |                                 | contact discharge                                       | -12  | +12  | kV   |
|           |                                 | air discharge                                           | -15  | +15  |      |
| $T_{amb}$ | ambient temperature             |                                                         | -40  | +85  | °C   |
| $T_{stg}$ | storage temperature             |                                                         | -55  | +125 | °C   |

## 6. Characteristics

**Table 5. Characteristics**

$T_{amb} = 25\text{ }^{\circ}\text{C}$  unless otherwise specified.

| Symbol            | Parameter                   | Conditions                                    | Min | Typ  | Max  | Unit          |
|-------------------|-----------------------------|-----------------------------------------------|-----|------|------|---------------|
| $V_{BR}$          | breakdown voltage           | $I_I = 1\text{ mA}$                           | 6   | -    | 9    | V             |
| $I_{RM}$          | reverse leakage current     | per channel; $V_I = 5\text{ V}$               | -   | -    | 1    | $\mu\text{A}$ |
| $V_F$             | forward voltage             | $I_I = 1\text{ mA}$                           | -   | 0.7  | -    | V             |
| $C_{line}$        | line capacitance            | $f = 1\text{ MHz}$ [1]                        |     |      |      |               |
|                   |                             | $V_I = 0\text{ V}$                            | -   | -    | 0.85 | pF            |
|                   |                             | $V_I = 2.5\text{ V}$                          | -   | -    | 0.75 | pF            |
| $\Delta C_{line}$ | line capacitance difference | $f = 1\text{ MHz}$ ; $V_I = 2.5\text{ V}$ [1] | -   | -    | 0.1  | pF            |
| $r_{dyn}$         | dynamic resistance          | surge [2]                                     |     |      |      |               |
|                   |                             | positive transient                            | -   | 0.42 | -    | $\Omega$      |
|                   |                             | negative transient                            | -   | 0.33 | -    | $\Omega$      |
|                   |                             | TLP [3]                                       |     |      |      |               |
|                   |                             | positive transient                            | -   | 0.42 | -    | $\Omega$      |
|                   |                             | negative transient                            | -   | 0.33 | -    | $\Omega$      |
| $V_{CL}$          | clamping voltage            | $I_{PP} = 4\text{ A}$ [2]                     |     |      |      |               |
|                   |                             | positive transient                            | -   | 4    | -    | V             |
|                   |                             | negative transient                            | -   | -2.3 | -    | V             |

[1] This parameter is guaranteed by design.

[2] According to IEC 61000-4-5 (8/20  $\mu\text{s}$  current waveform).

[3] 100 ns Transmission Line Pulse (TLP); 50  $\Omega$ ; pulser at 80 ns.

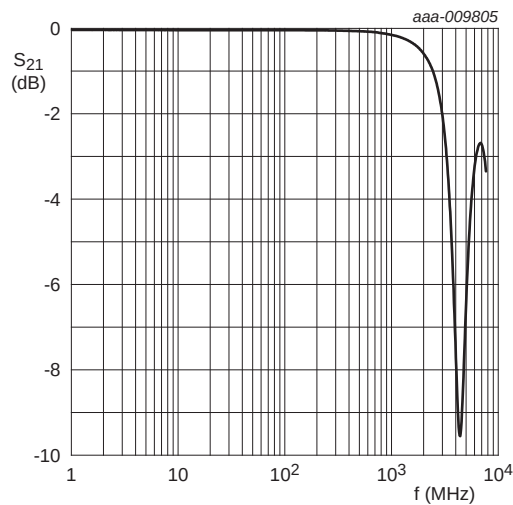


Fig 1. Insertion loss; typical values

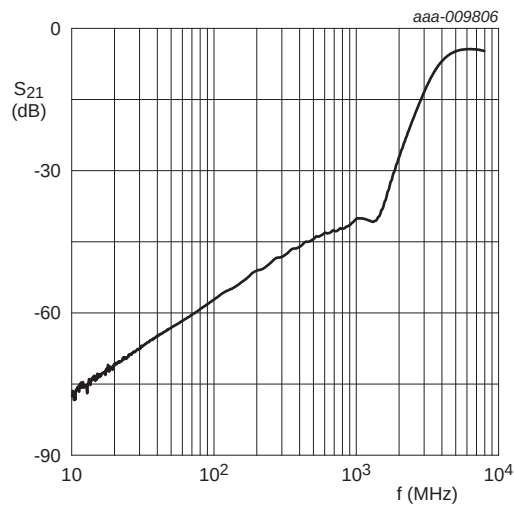
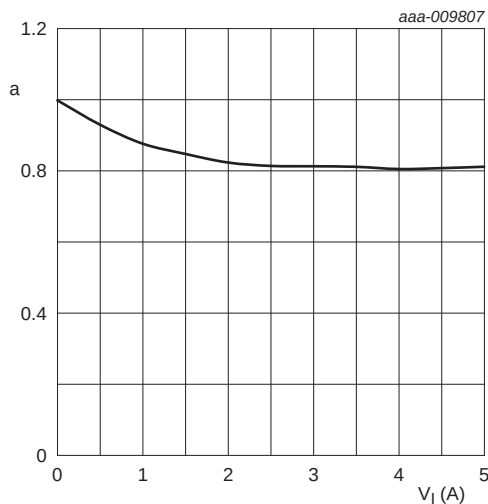
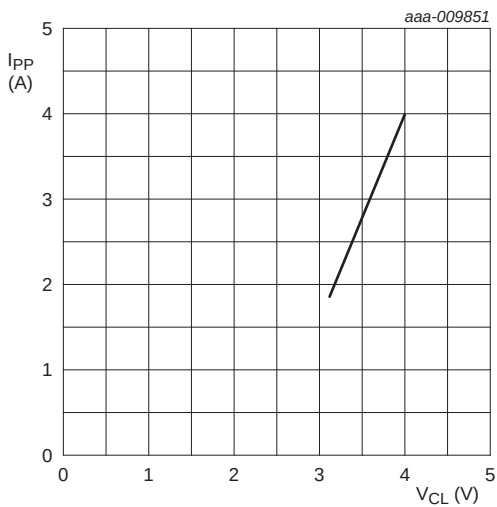


Fig 2. Crosstalk; typical values



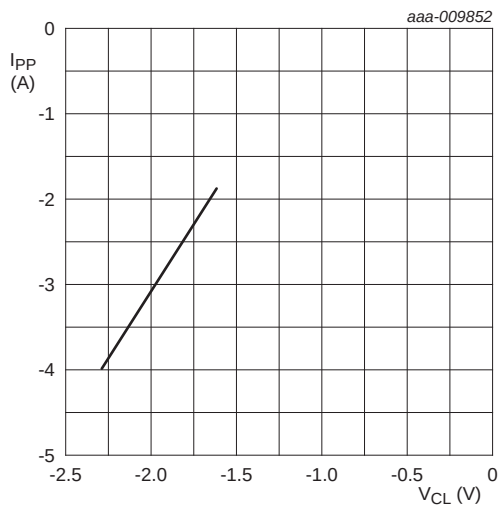
$$a = \frac{C_{line}}{C_{line}(V_I = 0 \text{ V})}$$

Fig 3. Relative capacitance as a function of input voltage; typical values



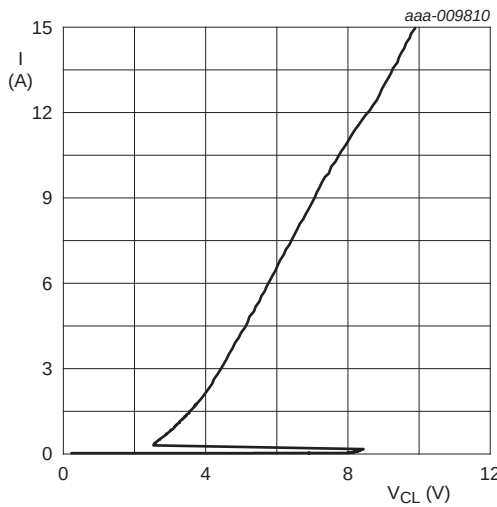
IEC 61000-4-5; t<sub>p</sub> = 8/20 μs; positive pulse

Fig 4. Dynamic resistance with positive clamping; typical values



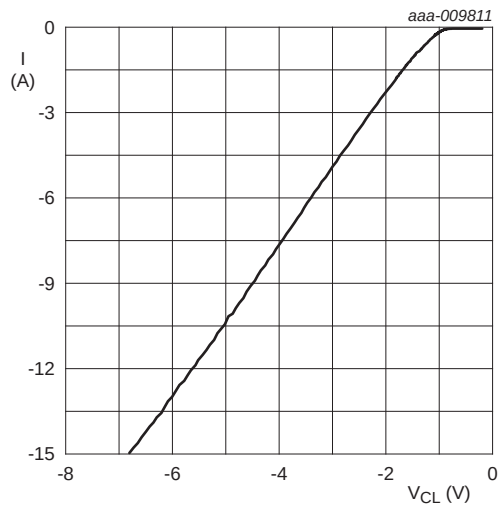
IEC 61000-4-5; t<sub>p</sub> = 8/20 μs; negative pulse

Fig 5. Dynamic resistance with negative clamping; typical values



t<sub>p</sub> = 100 ns; Transmission Line Pulse (TLP)

Fig 6. Dynamic resistance with positive clamping; typical values

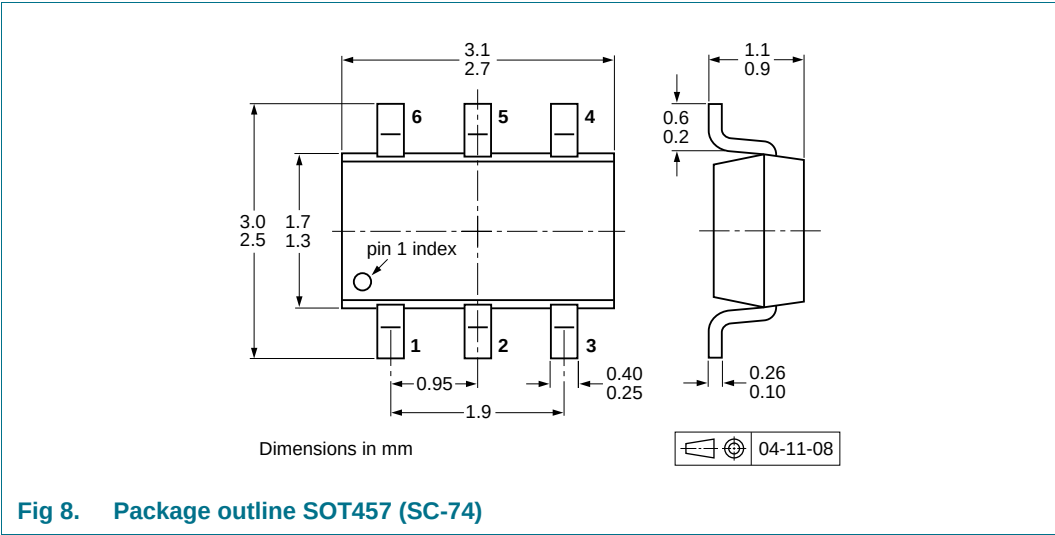


t<sub>p</sub> = 100 ns; Transmission Line Pulse (TLP)

Fig 7. Dynamic resistance with negative clamping; typical values

The device uses an advanced clamping structure, which shows a negative dynamic resistance. This snap-back behavior strongly reduces the clamping voltage to the system behind the ESD protection during an ESD event. Do not connect unlimited DC current sources to the data lines to avoid keeping the ESD protection device in snap-back state after exceeding breakdown voltage (due to an ESD pulse for instance).

7. Package outline



8. Soldering

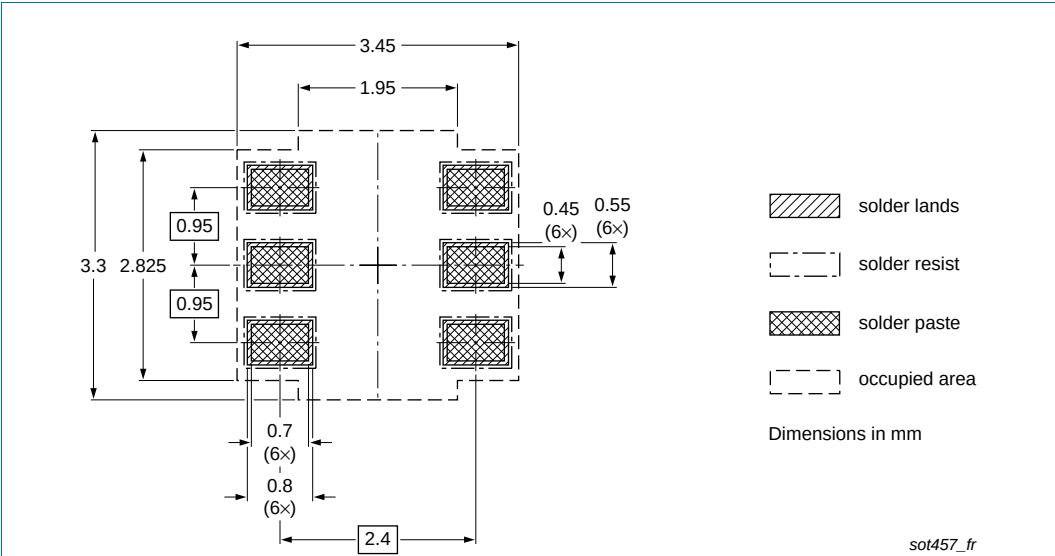


Fig 9. Reflow soldering footprint SOT457 (SC-74)

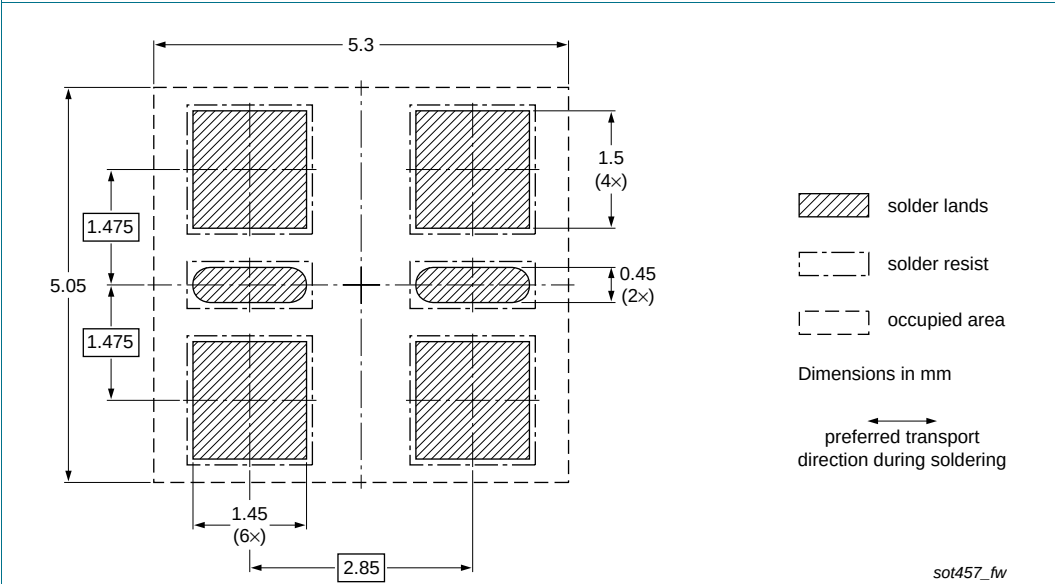


Fig 10. Wave soldering footprint SOT457 (SC-74)

## 9. Revision history

Table 6. Revision history

| Document ID      | Release date                                                                                                                                                                                                                                                   | Data sheet status      | Change notice | Supersedes       |
|------------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------------|---------------|------------------|
| IP4285CZ6-TD v.4 | 20140321                                                                                                                                                                                                                                                       | Product data sheet     | -             | IP4285CZ6-TD v.3 |
| Modifications:   | <ul style="list-style-type: none"><li>• <a href="#">Section 1 "Product profile"</a>: updated</li><li>• <a href="#">Figure 1</a> to <a href="#">7</a>: updated</li><li>• <a href="#">Table 4</a>: extended</li><li>• <a href="#">Table 5</a>: updated</li></ul> |                        |               |                  |
| IP4285CZ6-TD v.3 | 20121108                                                                                                                                                                                                                                                       | Product data sheet     | -             | IP4285CZ6-TD v.2 |
| IP4285CZ6-TD v.2 | 20111209                                                                                                                                                                                                                                                       | Preliminary data sheet | -             | IP4285CZ6-TD v.1 |
| IP4285CZ6-TD v.1 | 20111202                                                                                                                                                                                                                                                       | Objective data sheet   | -             | -                |



## 10. Legal information

### 10.1 Data sheet status

| Document status <sup>[1][2]</sup> | Product status <sup>[3]</sup> | Definition                                                                            |
|-----------------------------------|-------------------------------|---------------------------------------------------------------------------------------|
| Objective [short] data sheet      | Development                   | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet    | Qualification                 | This document contains data from the preliminary specification.                       |
| Product [short] data sheet        | Production                    | This document contains the product specification.                                     |

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[2] The term 'short data sheet' is explained in section "Definitions".

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